IPC ASSOCIATION ELECTRONIC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bo international and Pan-American copyright conventions.			nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				erials and N	Mfg Informati	ion			
Supplie	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority				Respon	Response Date*				
nsemi											2024-0	2024-05-02			
Contact N	Vame		Title - Contact			P	Phone - Contact*				Email	Email - Contact*			
Product-	Env-Stewards		Product Enviro Compliance			ľ	NA				Produ	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			P	Phone - Representative*				Email	Email - Representative*			
Product-	Env-Stewards		Product Enviro Compliance			r	NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version	on Manufacturing Site			Weight*	UOM	Unit Type	
		SZESD7104MUTAG BI-DIRECTIONAL		L 4 LINE TVS		2024-05-02		MY1			3.61	mg	Each		
Ianufa	acturing Process Inform				STD 000 M25						1		AD 0 -		
	8		· ·		-STD-020 MSL I	Rating				ture Max Time at Peak Temper			er of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	seco	onds 3			
omments															
	naximum time at peak tempera														
r more	information regarding materi	ial composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Die Attach Epoxy	0.01	mg		Epoxy resin	proprietary data		0.0065	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0035	mg
Lead Frame	1.11		Supplier	Tin (Sn)	7440-31-5		0.0028	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0024	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0028	mg
			Supplier	Copper (Cu)	7440-50-8		1.102	mg
Lead Frame plating	0.01	mg	Supplier	Silver (Ag)	7440-22-4		0.01	mg
Mold Compound-Black	2.25		Supplier	Epoxy and Phenolic Resin	40216-08-8		0.18	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0112	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.045	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.9462	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0675	mg
Plating	0.09	mg	Supplier	Tin (Sn)	7440-31-5		0.09	mg
Wire Bond - Au	0.09	mg	Supplier	Gold (Au)	7440-57-5		0.09	mg